



A DOCPHOENIX

Serial No. 09/577,457

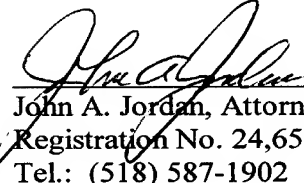
Atty. Doct No.: EN9-99-102US1

☒ Any additional filing fees required under 37 CFR §1.16. ☒ Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

Mark V. Pierson, et al.

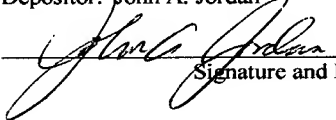
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CERTIFICATE OF MAILING UNDER 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<u>In Re Application of</u>	:	January 17, 2003
<u>Mark V. Pierson, et al.</u>	:	Examiner: J.M. Mitchell
<u>Serial No.: 09/577,457</u>	:	Art Unit: 2827
<u>Filed: May 24, 2000</u>	:	IBM Corporation Intellectual Property Law
<u>Title: FLOATING INTERPOSER</u>	:	Dept. N50/040-4, 1701 North Street Endicott, New York 13760

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Examiner's Office Action of December 3, 2002, please amend the application as follows:

In the Claims:

Please amend Claim 5 as follows:

- B'
- 1 5. (Twice Amended) An electronic package comprising:
 - 2 a semiconductor chip die having an array of conductive pads on one surface
 - 3 thereof;

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- 1 -

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